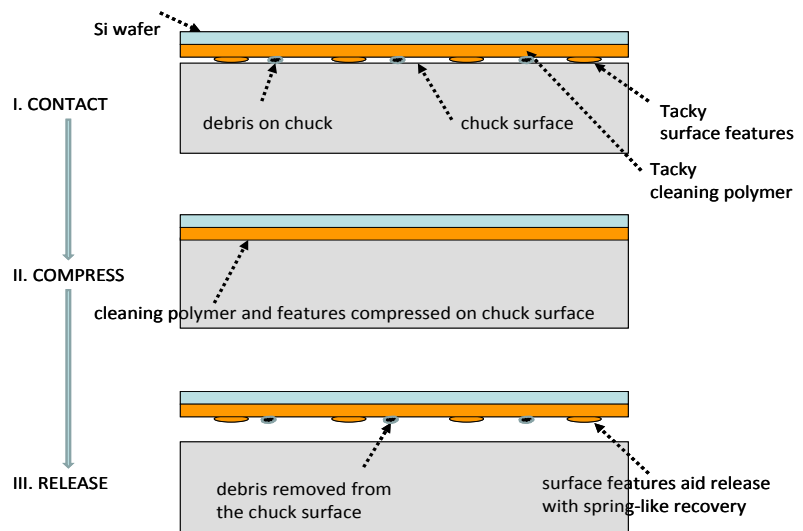
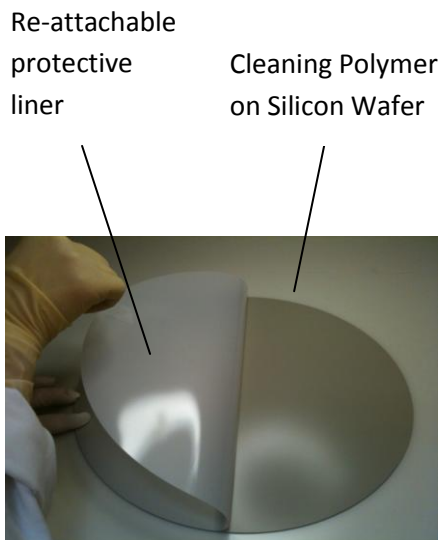


# Chuck Cleaning Wafer (CCW)

## Controlling Wafer Backside Debris

Engineered Multiple Use Cleaning Solutions for Wafer Handling Tools and Wafer Chuck

- CCW is a wafer constructed with an engineered surface geometry and tacky polymer film that is passed through wafer handling tools “tacky side down” to remove particles and debris via direct contact.
  - Meets appropriate SEMI Standards for all wafer diameters
  - Handled easily with existing hardware within wafer tools
  - Individual solutions are custom formulated to operate across -50C to 200C
- Polymer material is a non-Outgassing, proprietary material manufactured with controlled surface tackiness to collect and remove particles from wafer handling hardware, wafer tables, and wafer chucks.
  - 100% solid and highly cross-linked
  - Variable and highly controlled surface adhesion (“sticky surface”)
  - No residual transference during usage
  - Non out-gassing across operating ranges



**Compliant Edge Ring  
Wafer Handler Arm**



**Compliant Surface Eject  
Features for ESC Chuck**



**Compliant Spoke Features  
Pin Chuck and Handler**

Represented by; **SISTEM Technology**